ELECTRONIC AND ELECTRICAL TESTING
A core capability, we partner with the electronics and printed circuit board (PCB) industries. Our engineers routinely provide test program insight and development; allowing you the flexibility to enhance and/or structure programs to your specifications.

UL AND PRODUCT SAFETY TESTING
Element Anaheim can assist with UL Testing requirements for Printed Boards, Laminates and Coatings by helping to determine what materials and testing might be required before opening a full test program with UL. Testing the material and product before opening a full program could help understand material performance before submitting for final certification.

MICRO-SECTIONAL ANALYSIS
We offer one of the most proven methods to accurately test for the through-hole integrity of printed circuit boards. Since PCBs are constructed of various materials and layers including glass, fibers, metals, adhesives and epoxies, it is critical to product safety to determine the reliability of PCB microsections. In addition, we offer micro-sectional analysis training, so your staff can perform this testing in-house if you prefer.

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DEVELOPING INNOVATIVE PRODUCT TESTING AND CERTIFICATION SOLUTIONS

RESEARCH AND DEVELOPMENT

Our Research and Development team has more than 25 years of experience providing R&D test services, analysis and consulting on electronics and materials. Our laboratories are equipped with the most advanced instrumentation to customize a program to best meet your development requirements. A partial list of our R&D capabilities includes:

- Accelerated aging
- Differential Scanning Calorimetry (DSC)
- Failure Analysis (F/A)
- Thermal Conductivity
- Thermal Mechanical Analysis (TMA)
- X-Ray Fluorescence (XRF)

TEST SPECIFICATIONS AND METHODS INCLUDE:

- Accelerated aging
- Adhesion
- Arc resistance
- Ball shear/die sheet
- Ball pressure test
- Bond strength
- Break strength
- Comparative Tracking Index (CTI)
- Compressive strength
- Conductivity
- Conductive anodic filament (CAF)
- Conformance and reliability
- Corrosion
- DC resistance insulating materials
- Dielectric breakdown/strength
- Decapsulation
- Deflection temperature
- Design of experiments (DOE)
- Density determination
- Dielectric breakdown voltage and strength
- Differential scanning calorimetry (DSC)

- Durability
- Electromigration resistance
- Elongation
- Environmental stress screening (ESS)
- Flammability
- Flexibility endurance
- Flexural bend/fatigue/strength
- Fracture evaluation
- Fracture toughness
- Hi-Pot
- High temperature storage
- High-voltage, low current dry arc
- Hot impact test
- Humidity
- Immersion
- Microsectional analysis
- Surface insulation resistance (SIR)
- Volume/surface resistivity
- Lap shear
- Material characterization
- Mechanical properties
- Peel/sheer/tensile/terminal strength
- Rework simulation
- Rockwell hardness
- Solderability
- Steam aging
- Temperature aging/cycling
- Tensile impact
- Tension and compression
- Thermal shock/cycling
- Thermal stress
- Thermo gravimetric analysis (TGA)
- UL short-term properties
- UL long-term thermal aging (LTTA)
- Water absorption
- Dielectric withstanding voltage (DWV)
- Wire ignition
- X-Ray fluorescence (XRF)
- Young's Modulus